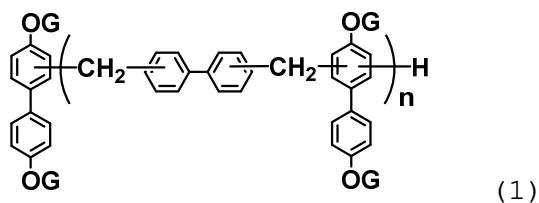


[ABSTRACT]

EPOXY RESIN COMPOSITION AND CURED PRODUCT OF SAME

Provided is an epoxy resin composition that is particularly suitable for power semiconductor sealing and makes it possible to obtain an epoxy resin cured product that is particularly excellent in tracking resistance and also excellent in balance thereof with heat resistance and in thermal decomposition stability; and also provided are an epoxy resin cured product and a semiconductor. The epoxy resin composition includes, as essential components: (A) an epoxy resin represented by a general formula (1) below; (B) a non-aromatic epoxy resin or a non-silicone rubber having a 5% weight loss temperature of 260°C or higher; (C) a curing agent; and (D) a curing accelerator, wherein the component (B) is contained in an amount of 1% by weight to 50% by weight with respect to a total amount of the components (A) to (D):

[C1]



where, n represents a number of 0 to 20 and G represents a glycidyl group.